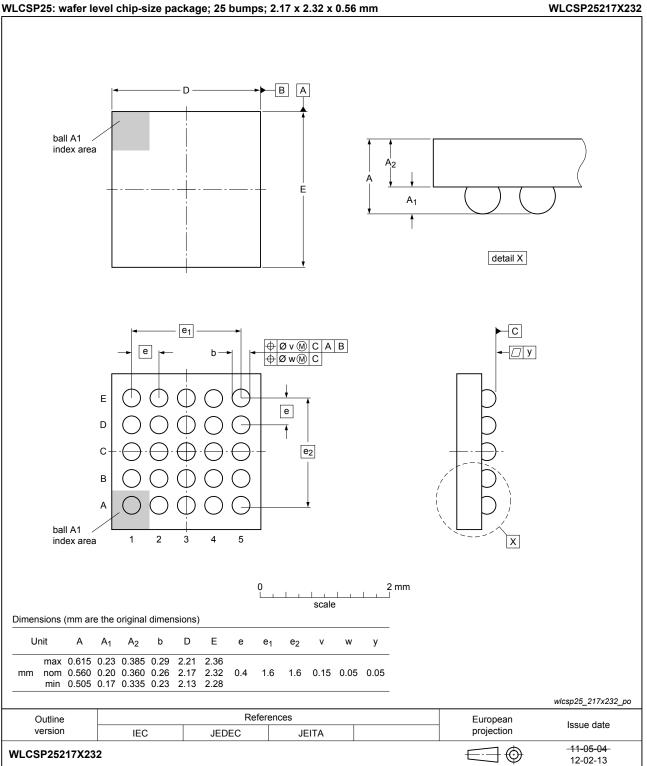


Package outline



WLCSP25: wafer level chip-size package; 25 bumps; 2.17 x 2.32 x 0.56 mm

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Printed in the Netherlands